

| Ref # | Hits | Search Query    | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|-----------------|---|------------------|---------|------------------|
| S1    | 439  | (118/666).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:57 |
| S2    | 397  | (118/679).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:53 |
| S3    | 192  | (118/680).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:53 |
| S4    | 290  | (118/667).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:57 |
| S5    | 263  | (118/669).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:58 |
| S6    | 103  | (118/677).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:58 |
| S7    | 541  | (118/313).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:58 |
| S8    | 820  | (118/314).CCLS. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/03/21 02:58 |

|     |     |   |   |    |     |                  |
|-----|-----|---|---|----|-----|------------------|
| S9  | 864 | (118/315).CCLS.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/03/21 02:58 |
| S10 | 75  | (S1 S2 S3 S4 S5 S6 S7 S8 S9) and<br>(sealant or resin or paste) and<br>(semiconductor)                        | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2005/03/21 03:21 |
| S11 | 1   | ("5932012").PN.   | USPAT   | OR | OFF | 2005/03/21 03:32 |
| S12 | 4   | ("5932012").URPN.   | USPAT   | OR | ON  | 2005/03/21 03:19 |
| S13 | 2   | ("5415693"   "5437727").PN.   | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR | ON  | 2005/03/21 03:20 |
| S14 | 87  | (substrate near3 (heat or heater))<br>and (sealant near4 (resin or paste))<br>and (semiconductor) and control | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2005/03/21 03:22 |
| S15 | 1   | ("5906682").PN.   | USPAT   | OR | OFF | 2005/03/21 03:32 |